

## Structure and Process for Packaging Back-to-Back Chips

### Abstract

5        A packaging structure for back-to-back chips, which includes: a  
substrate, a first chip, a second chip, and an encapsulation. Wherein, the  
first chip has an active side and an inactive side, and the active side of the  
first chip is connected to the substrate by an adhesion layer and conducted  
electrically with the substrate by wire-bonding. The second chip has an  
10    active side that is also conducted electrically with the substrate by  
wire-bonding and an inactive side that is connected to the inactive side of  
the first chip by another adhesion layer. The encapsulation covers both the  
first chip and the second chip for protecting the back-to-back packaging  
structure.